SEMICONDUCTOR DEVICE

Abstract of the Disclosure

An aluminum-nickel-chromium (Al-Ni-Cr) layer (34) is used as an interconnect (31) within a semiconductor device. The Al-Ni-Cr layer (34) has about 0.1-0.5 weight percent nickel and about 0.02-0.1 weight percent chromium. Usually, the nickel or chromium concentrations are no greater than 0.5 weight percent. The layer (34) is resistant to electromigration and corrosion. The low nickel and chromium concentrations allow the layer (34) to be deposited and patterned similar to most aluminum-based layers.

FIG. 3 accompanies this abstract.